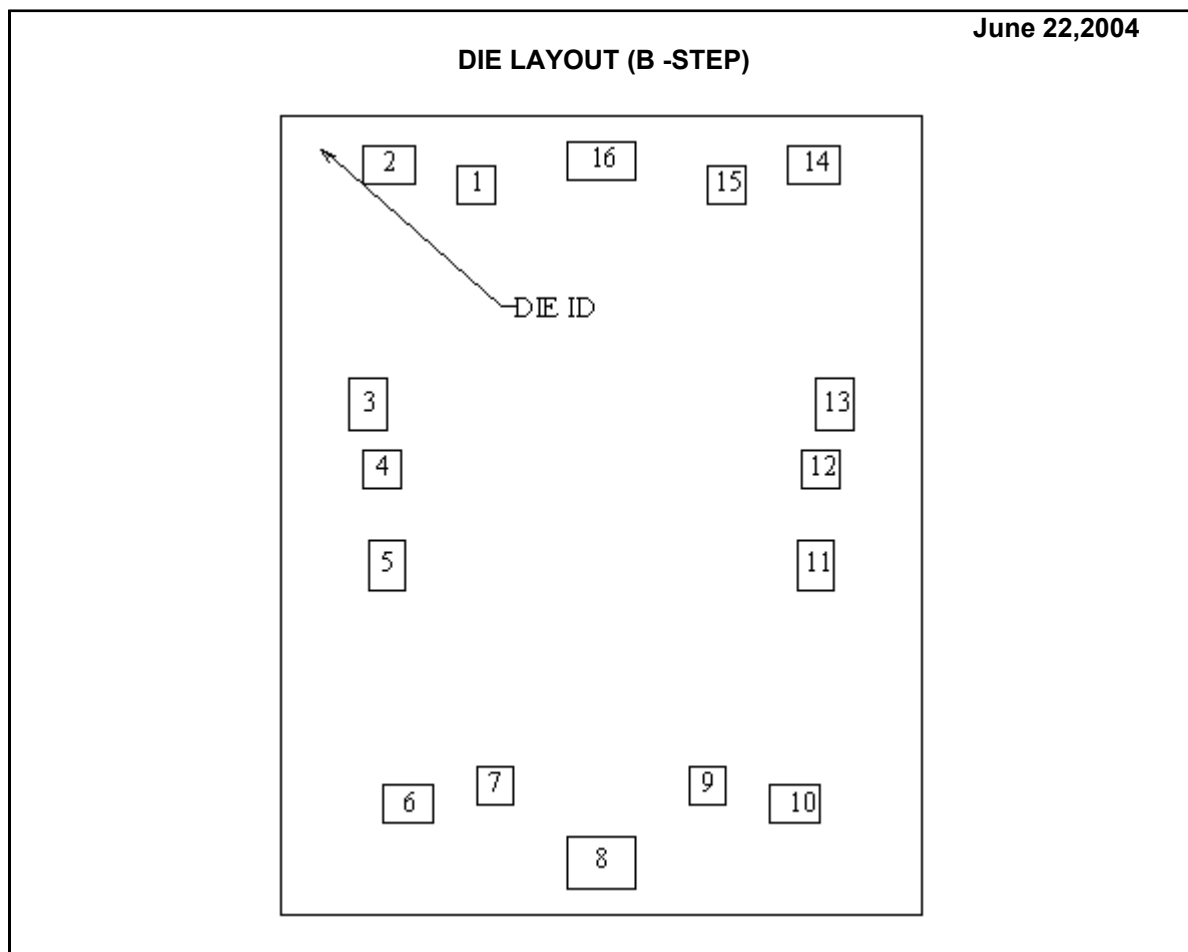


DS26LS31C MDC MWC
QUAD HIGH SPEED DIFFERENTIAL LINE DRIVER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	26LS31B	Bond Pad Opening Size (min)	102 μ m x 102 μ m
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	NITRIDE
Wafer Diameter	100 or 150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1727 μ m x 2159 μ m 68.0mils x 85.0mils	Back Side Connection	Floating
Thickness	330 μ m Nominal		
Min Pitch	211 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
INPUT A	1	-338	893	102	x	102
CH A OUTPUT	2	-574	946	137	x	102
CH A OUTPUT	3	-630	301	102	x	137
ENABLE	4	-592	123	102	x	102
CH B OUTPUT	5	-579	-136	102	x	137
CH B OUTPUT	6	-523	-781	137	x	102
INPUT B	7	-287	-728	102	x	102
GND	8	0	-937	188	x	140
INPUT C	9	287	-728	102	x	102
CH C OUTPUT	10	523	-781	137	x	102
CH C OUTPUT	11	579	-136	102	x	137
/ENABLE	12	592	123	102	x	102
CH D OUTPUT	13	630	301	102	x	137
CH D OUTPUT	14	574	946	137	x	102
INPUT D	15	338	893	102	x	102
VCC	16	0	956	188	x	102

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